



2023 IEEE Workshop on Microelectronics & Electron Devices

March 31, 2023

Stueckle Skye Center, Boise State University

WMED Highlights:

- Two parallel tutorials
- Best paper and poster awards
- Past Invited Speakers
 - Dr. Kaustav Banerjee, UCSB [2021]
 - Dr. Eric Pop, Stanford [2019]
 - Dr. Daniel Friedman, IBM [2018]
 - Ted Taylor, ASML [2017]
 - Larry Smith, Qualcomm [2016]

Important Dates:

- Manuscript submission: 1/6/2023
- Advance registration: 3/24/2023
- Conference date: 3/31/2023

Micron Authors: Before submitting your manuscript to the WMED technical committee for consideration, please ensure that a) you have the required area and legal approvals for external publication, and b) the manuscript is in the required IEEE format for publication. For TPG manuscripts, the internal review may take up to 15 business days, and therefore, the authors are encouraged to initiate the internal review process well before the 1/6/2023 deadline. TPG internal review details are at the alias pubreview/.

WMED 2023 – Call for Papers

The Twentieth Annual IEEE Workshop on Microelectronics and Electron Devices (WMED) will provide a forum for reviewing and discussing all aspects of micro- and nano-electronics including processing, electrical characterization, design, and new device technologies. This workshop will consist of invited and contributed talks, papers, and a poster session throughout the day. Faculty, students, and researchers in industry are encouraged to contribute papers on either completed research or work in progress. Topics in the following areas will form the contributing sessions and poster session in the workshop:

Microelectronic Device Processing and Process Integration

Trends in submicron CMOS technology, product development (DRAM, SRAM, Flash, CMOS Imagers), new device technologies (phase change memory, resistive memory, ferroelectric memory), novel transistors

Nanoelectronic Devices and MEMS

Novel processes, materials and device characterization on nanotubes, nanowires, quantum dots, molecular devices, MEMS research

Microelectronic Device Electrical and Reliability Testing

Dielectric reliability, device reliability, novel memory technology testing schemes

Semiconductor Packaging and Reliability

Semiconductor package reliability, design for manufacturability, stacked die packaging, and novel assembly processes

Microelectronic Circuit and System Design

New product design, high-speed and low-power design techniques and system architectures and memory sensing schemes

An IEEE Publication of the accepted papers and presentations will be available digitally at the start of the workshop. Submitted manuscripts must follow the IEEE publication format guidelines. A template containing manuscript preparation instructions can be downloaded here:

[Download Manuscript Template](#)

Please submit your IEEE-formatted manuscript (up to 4 pages) by January 6, 2023 to the WMED Publications Chair, Saumil Joshi (saumiljoshi@micron.com, or saumil.joshi@ieee.org, +1 208-368-5455). The Technical Program Committee will have a peer-review process to meet the IEEE criterion for minimum standards of publication quality. Inquiries can be directed to Durga Panda (IEEE WMED 2023 General Chair, dpanda@micron.com, +1 515-231-6022).